

# FDC642P

## Single P-Channel 2.5V Specified PowerTrench® MOSFET

-20 V, -4.0 A, 65 mΩ

### Features

- Max  $r_{DS(on)}$  = 65 mΩ at  $V_{GS} = -4.5$  V,  $I_D = -4.0$  A
- Max  $r_{DS(on)}$  = 100 mΩ at  $V_{GS} = -2.5$  V,  $I_D = -3.2$  A
- Fast switching speed
- Low gate charge (11nC typical)
- High performance trench technology for extremely low  $r_{DS(on)}$
- SuperSOT™-6 package: small footprint (72% smaller than standard SO-8); low profile (1 mm thick)
- Termination is Lead-free and RoHS Compliant



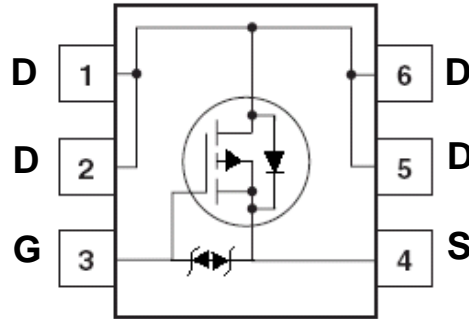
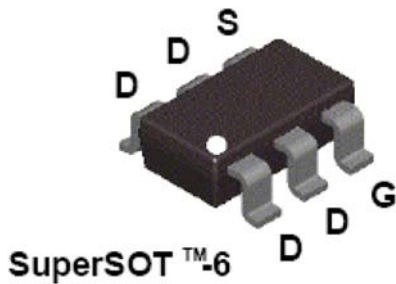
### General Description

This P-Channel 2.5V specified MOSFET is produced using Fairchild's advanced PowerTrench® process that has been especially tailored to minimize on-state resistance and yet maintain low gate charge for superior switching performance.

These devices have been designed to offer exceptional power dissipation in a very small footprint for applications where the larger packages are impractical.

### Applications

- Load switch
- Battery protection
- Power management



### MOSFET Maximum Ratings $T_C = 25^\circ\text{C}$ unless otherwise noted

Symbol	Parameter	Ratings	Units
$V_{DS}$	Drain to Source Voltage	-20	V
$V_{GS}$	Gate to Source Voltage	±8	V
$I_D$	-Continuous $T_A = 25^\circ\text{C}$ (Note 1a)	-4.0	A
	-Pulsed	-20	
$P_D$	Power Dissipation (Note 1a)	1.6	W
	Power Dissipation (Note 1b)	0.8	
$T_J, T_{STG}$	Operating and Storage Junction Temperature Range	-55 to + 150	°C

### Thermal Characteristics

$R_{\theta JA}$	Thermal Resistance, Junction to Ambient (Note 1a)	78	°C/W
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### Package Marking and Ordering Information

Device Marking	Device	Package	Reel Size	Tape Width	Quantity
.642	FDC642P	SSOT-6™	7"	8 mm	3000 units

## Electrical Characteristics $T_J = 25^\circ\text{C}$ unless otherwise noted

Symbol	Parameter	Test Conditions	Min	Typ	Max	Units
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### Off Characteristics

$BV_{DSS}$	Drain to Source Breakdown Voltage	$I_D = -250 \mu\text{A}, V_{GS} = 0 \text{ V}$	-20			V
$\frac{\Delta BV_{DSS}}{\Delta T_J}$	Breakdown Voltage Temperature Coefficient	$I_D = -250 \mu\text{A}$ , referenced to $25^\circ\text{C}$		-13		mV/ $^\circ\text{C}$
$I_{DSS}$	Zero Gate Voltage Drain Current	$V_{DS} = -16 \text{ V}, V_{GS} = 0 \text{ V}$			-1	$\mu\text{A}$
$I_{GSS}$	Gate to Source Leakage Current	$V_{GS} = \pm 8 \text{ V}, V_{DS} = 0 \text{ V}$			$\pm 10$	$\mu\text{A}$

### On Characteristics

$V_{GS(th)}$	Gate to Source Threshold Voltage	$V_{GS} = V_{DS}, I_D = -250 \mu\text{A}$	-0.4	-0.6	-1.5	V
$\frac{\Delta V_{GS(th)}}{\Delta T_J}$	Gate to Source Threshold Voltage Temperature Coefficient	$I_D = -250 \mu\text{A}$ , referenced to $25^\circ\text{C}$		2.5		mV/ $^\circ\text{C}$
$r_{DS(on)}$	Static Drain to Source On Resistance	$V_{GS} = -4.5 \text{ V}, I_D = -4.0 \text{ A}$		45	65	m $\Omega$
		$V_{GS} = -2.5 \text{ V}, I_D = -3.2 \text{ A}$		55	100	
		$V_{GS} = -4.5 \text{ V}, I_D = -4.0 \text{ A}, T_J = 125^\circ\text{C}$		62	90	
$g_{FS}$	Forward Transconductance	$V_{DS} = -5 \text{ V}, I_D = -4.0 \text{ A}$		15		S

### Dynamic Characteristics

$C_{iss}$	Input Capacitance	$V_{DS} = -10 \text{ V}, V_{GS} = 0 \text{ V}, f = 1 \text{ MHz}$		700	925	pF
$C_{oss}$	Output Capacitance			110	150	pF
$C_{rss}$	Reverse Transfer Capacitance			95	145	pF

### Switching Characteristics

$t_{d(on)}$	Turn-On Delay Time	$V_{DD} = -10 \text{ V}, I_D = -1 \text{ A}, V_{GS} = -4.5 \text{ V}, R_{GEN} = 6 \Omega$		6	12	ns
$t_r$	Rise Time			7	14	ns
$t_{d(off)}$	Turn-Off Delay Time			120	190	ns
$t_f$	Fall Time			52	83	ns
$Q_g$	Total Gate Charge			11	16	nC
$Q_{gs}$	Gate to Source Charge	$V_{DD} = -10 \text{ V}, I_D = -4 \text{ A}, V_{GS} = -4.5 \text{ V}$		1.1		nC
$Q_{gd}$	Gate to Drain "Miller" Charge			3.0		nC

### Drain-Source Diode Characteristics

$I_S$	Maximum Continuous Drain-Source Diode Forward Current				-1.3	A
$V_{SD}$	Source-Drain Diode Forward Voltage	$V_{GS} = 0 \text{ V}, I_S = -1.3 \text{ A}$ (Note 2)		-0.7	-1.2	V

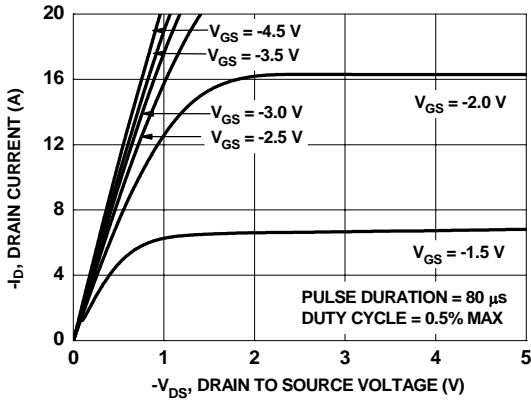
#### Notes:

1:  $R_{\theta JA}$  is the sum of the junction-to-case and case-to-ambient thermal resistance where the case thermal reference is defined as the solder mounting surface of the drain pins.  $R_{\theta JC}$  is guaranteed by design while  $R_{\theta CA}$  is determined by the user's board design.

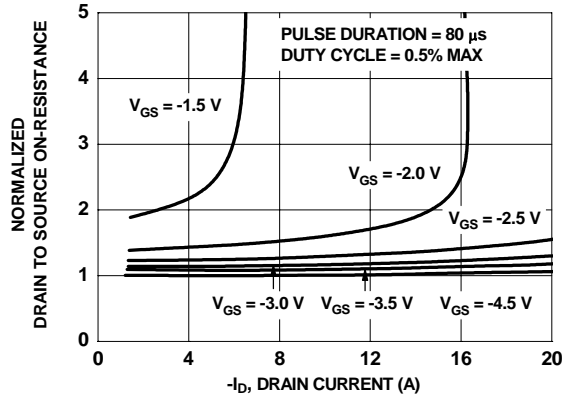
- a.  $78^\circ\text{C/W}$  when mounted on a  $1 \text{ in}^2$  pad of 2 oz copper.
- b.  $156^\circ\text{C/W}$  when mounted on a minimum pad of 2 oz copper.

2: Pulse Test: Pulse Width < 300  $\mu\text{s}$ , Duty Cycle < 2.0%.

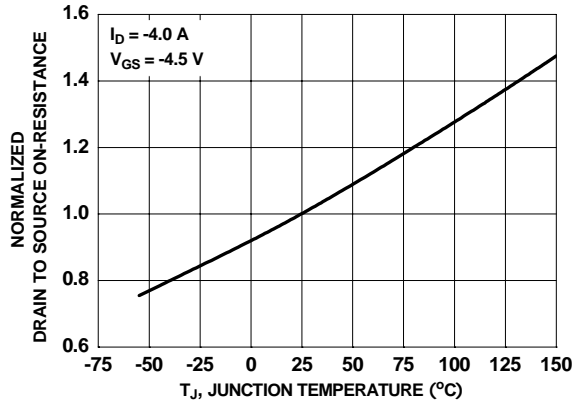
**Typical Characteristics**  $T_J = 25^\circ\text{C}$  unless otherwise noted



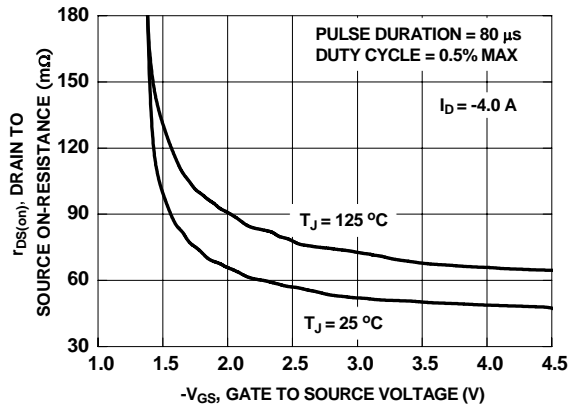
**Figure 1. On Region Characteristics**



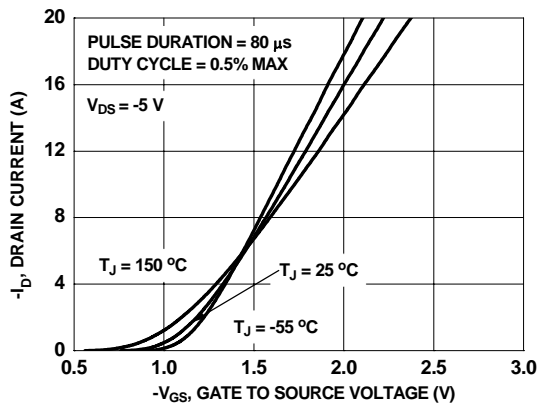
**Figure 2. Normalized On-Resistance vs Drain Current and Gate Voltage**



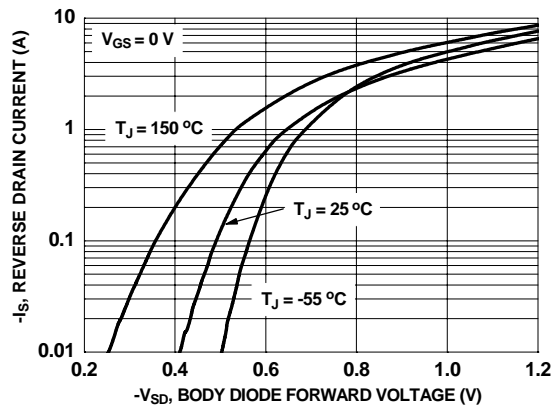
**Figure 3. Normalized On Resistance vs Junction Temperature**



**Figure 4. On-Resistance vs Gate to Source Voltage**

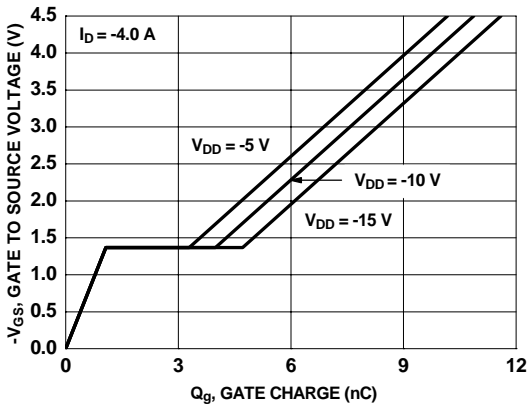


**Figure 5. Transfer Characteristics**

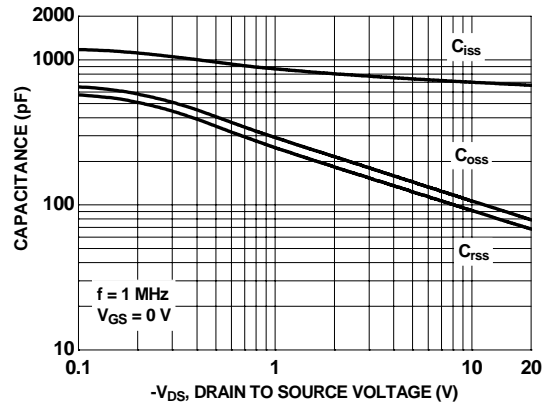


**Figure 6. Source to Drain Diode Forward Voltage vs Source Current**

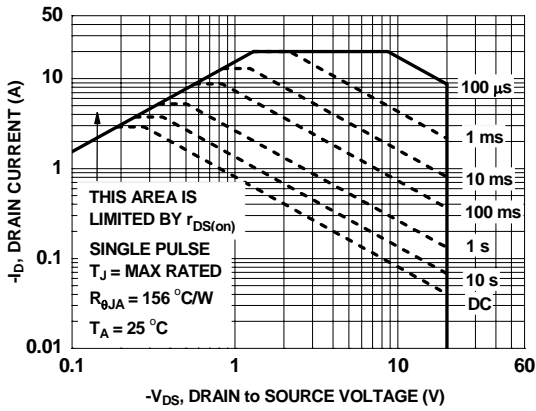
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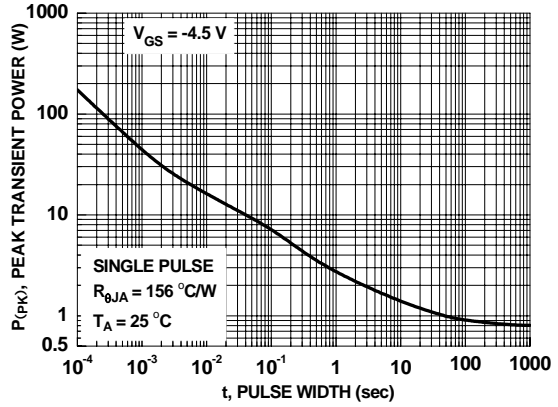
**Figure 7. Gate Charge Characteristics**



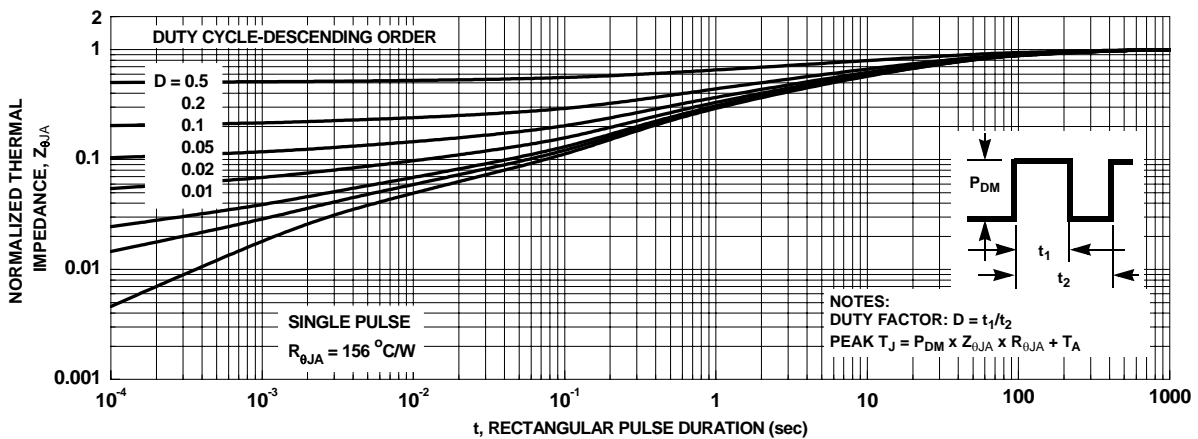
**Figure 8. Capacitance vs Drain to Source Voltage**



**Figure 9. Forward Bias Safe Operating Area**



**Figure 10. Single Pulse Maximum Power Dissipation**





**Figure 11. Junction-to-Ambient Transient Thermal Response Curve**






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